

SEMIPACK® 3

Thyristor Modules

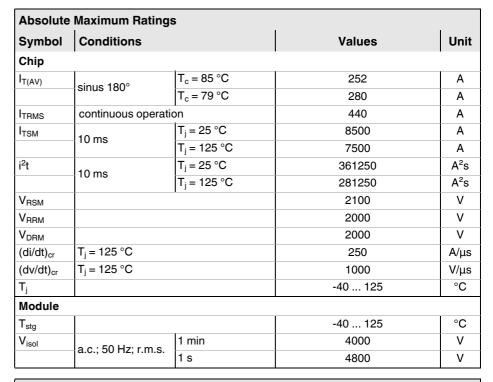
SKKT 280/20 E H4

Features

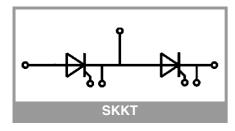
- Heat transfer through aluminium nitride ceramic isolated metal baseplate
- Precious metal pressure contacts for high reliability
- · Thyristor with amplifying gate
- UL recognized, file no. E 63 532

Typical Applications*

- DC motor control (e. g. for machine tools)
- AC motor starters
- Temperature control (e. g. for ovens, chemical processes)
- Professional light dimming (studios, theaters)



Characte	ristics					
Symbol	Conditions	min.	typ.	max.	Unit	
Chip						
V _T	$T_j = 25 ^{\circ}\text{C}, I_T = 750 \text{A}$				1.55	V
$V_{T(TO)}$	T _j = 125 °C				0.9	V
r _T	T _j = 125 °C				0.75	mΩ
$I_{DD};I_{RD}$	$T_j = 125 ^{\circ}\text{C}, V_{DD} = V_{DRM}; V_{RD} = V_{RRM}$				90	mA
t _{gd}	$T_j = 25 ^{\circ}\text{C}, I_G = 1 \text{A}, di_G/dt = 1 \text{A}/\mu\text{s}$			1		μs
t _{gr}	$V_D = 0.67 * V_{DRM}$			2		μs
tq	T _j = 125 °C		50	150	150	μs
I _H	T _j = 25 °C			150	500	mA
IL	$T_j = 25 ^{\circ}\text{C}, R_G = 33 \Omega$			300	2000	mA
V _{GT}	$T_j = 25$ °C, d.c.		3			V
I _{GT}	$T_j = 25$ °C, d.c.		200			mA
V_{GD}	$T_j = 125$ °C, d.c.				0.25	V
I_{GD}	$T_j = 125$ °C, d.c.				10	mA
$R_{\text{th(j-c)}}$	continuous DC	per chip			0.11	K/W
		per module			0.055	K/W
R _{th(j-c)}	sin. 180°	per chip			0.116	K/W
		per module			0.058	K/W
R _{th(j-c)}	rec. 120°	per chip			0.13	K/W
		per module			0.065	K/W
Module						
R _{th(c-s)}	chip			0.04		K/W
	module			0.02		K/W
Ms	to heatsink M5		4.25		5.75	Nm
Mt	to terminals M8		7.65		10.34	Nm
а					5 * 9,81	m/s²
W				600		g



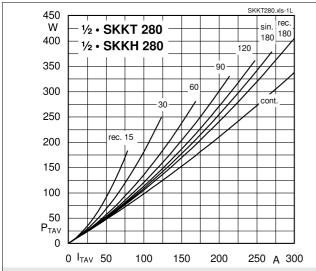


Fig. 1L: Power dissipation per thyristor vs. on-state current

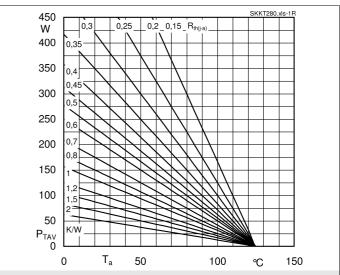


Fig. 1R: Power dissipation per thyristor vs. ambient temperature

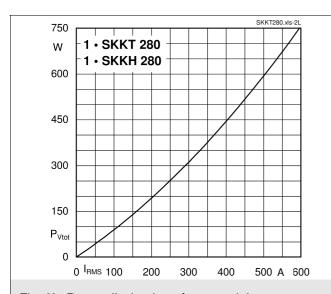


Fig. 2L: Power dissipation of one module vs. rms current

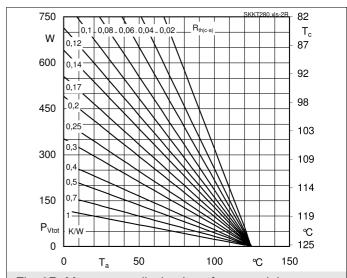


Fig. 2R: Max. power dissipation of one module vs. case temperature

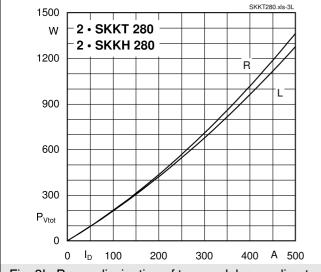


Fig. 3L: Power dissipation of two modules vs. direct current

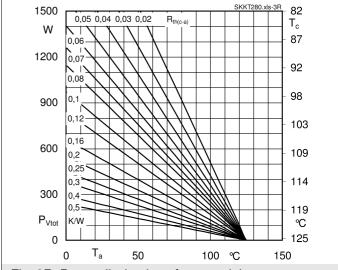


Fig. 3R: Power dissipation of two modules vs. case temperature

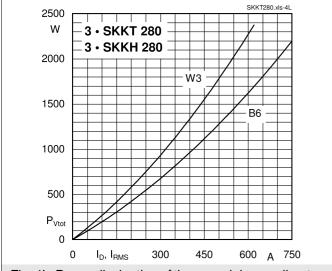


Fig. 4L: Power dissipation of three modules vs. direct and rms current

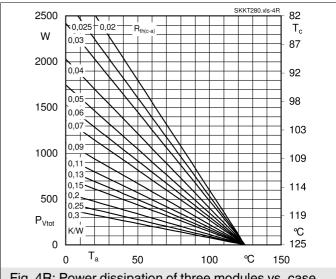


Fig. 4R: Power dissipation of three modules vs. case temperature

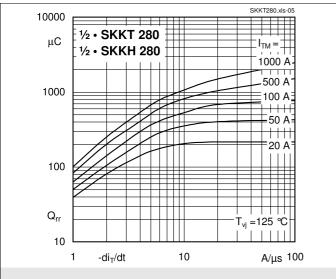


Fig. 5: Recovered charge vs. current decrease

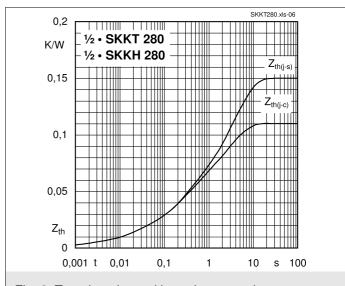


Fig. 6: Transient thermal impedance vs. time

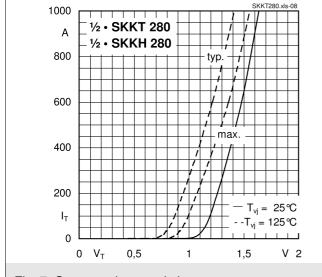
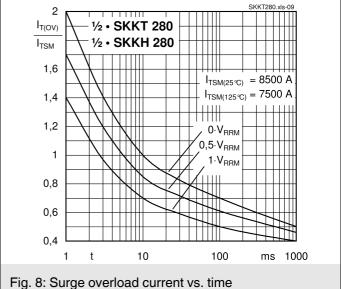
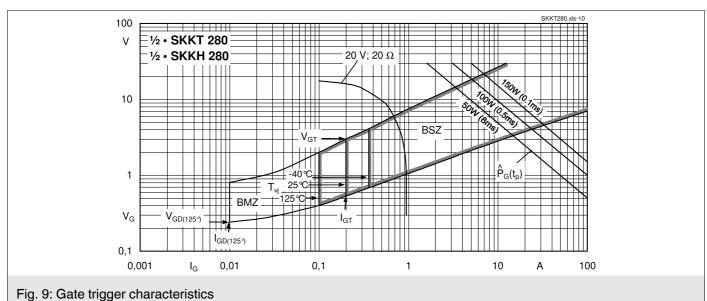
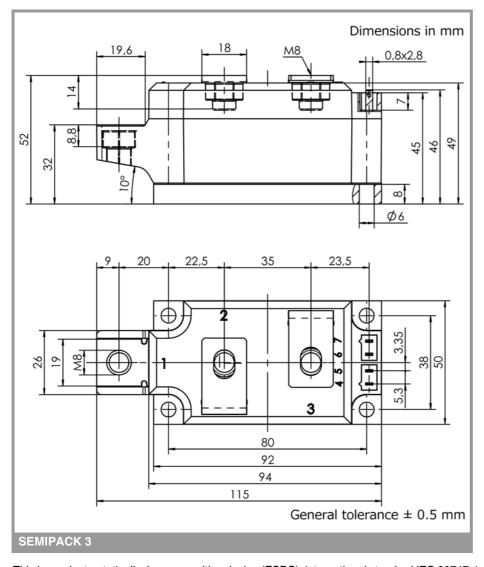


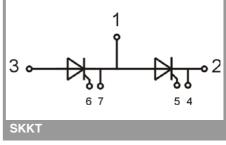
Fig. 7: On-state characteristics





rig. 9. date trigger characteristics





This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

*IMPORTANT INFORMATION AND WARNINGS

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